



## Material Content Data Sheet



<b>Sales Product Name</b>		SPD09P06PL G		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000446596						
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		313.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.145	0.37	0.37	3652	3652
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		457	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	copper	7440-50-8	143.098	45.65	45.71	456470	457064
wire	non noble metal	aluminium	7429-90-5	5.023	1.60	1.60	16023	16023
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.955	0.62		6238	
	plastics	brominated resin	-	2.095	0.67		6683	
	organic material	carbon black	1333-86-4	2.235	0.71		7129	
	plastics	epoxy resin	-	18.856	6.01		60149	
	inorganic material	silicondioxide	60676-86-0	114.533	36.53	44.54	365350	445549
leadfinish	non noble metal	tin	7440-31-5	3.787	1.21	1.21	12080	12080
plating	non noble metal	nickel	7440-02-0	0.086	0.03		276	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	277
solder	noble metal	silver	7440-22-4	0.032	0.01		103	
	non noble metal	tin	7440-31-5	0.026	0.01		82	
	non noble metal	lead	7439-92-1	1.228	0.39	0.41	3917	4102
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.12	6.13	61174	61253
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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